



QDD-400GB-DCO-ZRP-1DBM-C-SKY

Cisco® Compatible 400GBase-Open ZR+ Coherent QSFP-DD Transceiver (SMF, 1528.77nm to 1567.13nm, 120km, LC, DOM, 1dBm)

Product Description

This Cisco® compatible QSFP-DD transceiver provides 400GBase-Open ZR+ throughput up to 120km over single-mode fiber (SMF) using a wavelength of 1528.77nm to 1567.13nm via an LC connector. It can operate at temperatures between 0 and 70C. Our transceiver is built to meet or exceed OEM specifications and is guaranteed to be 100% compatible with Cisco®. It has been programmed, uniquely serialized, and tested for data-traffic and application to ensure that it will initialize and perform identically. All of our transceivers comply with Multi-Source Agreement (MSA) standards to provide seamless network integration. Additional product features include Digital Optical Monitoring (DOM) support which allows access to real-time operating parameters. We stand behind the quality of our products and proudly offer a limited lifetime warranty.

Skylane's transceivers are RoHS compliant and lead-free.

Features:

- Hot Pluggable QSFP-DD Footprint (Type 2A)
- Duplex LC Connector
- Supports 400/300/200/100Gbps
- Coherent Receivers
- Power Dissipation is 26.1W
- Tunable C-Band Transmitter
- Operating Case Temperature: 15 to 75 Celsius
- Single +3.3V Power Supply
- Supports both CFEC and oFEC
- Tunable Output Power: -9dBm to +1dBm
- RoHS Compliant and Lead Free



Applications:

- 400GBase Ethernet
- IP-over-DWDM
- Open ZR+

For your product safety, please read the following information carefully before any manipulation of the transceiver:



ESD

This transceiver is specified as ESD threshold 1kV for SFI pins and 2kV for all others electrical input pins, tested per MIL-STD-883G, Method 3015.4 /JESD22-A114-A (HBM). However, normal ESD precautions are still required during the handling of this module.



LASER SAFETY

This is a Class1 Laser Product according to IEC 60825-1:2007. This product complies with 21 CFR 1040.10 and 1040.11 except for deviations pursuant to Laser Notice No. 50, dated (June 24, 2007).

The optical ports of the module need to be terminated with an optical connector or with a dust plug in order to avoid contamination.

Application Codes

Application Code	Host Format	Payload Rate	Media Format	FEC	Modulation	Description	Media Lane Interface	Default: Enhanced Mode (S=Standard, E=Enhanced)
1	1 x 400GAUI-8	400G	ZR	CFEC	16QAM	OIF 400ZR app codes 0x01, 0x03	400G-400ZR-CFEC-16QAM-1-S	S
2	1 x 400GAUI-8	400G	ZR	CFEC	16QAM	OIF 400ZR app code 0x02	400G-400ER-CFEC-16QAM-1-S	S
3	1 x 400GAUI-8	400G	OpenZR+	oFEC	16QAM	OpenZR+ MSA	400G-400ZR-oFEC-16QAM-1-S	S
4	2 x 200GAUI-4	400G	OpenZR+	oFEC	16QAM	OpenZR+ MSA	200G-400ZR-oFEC-16QAM-1-S	S
5	4 x 100GAUI-2	400G	OpenZR+	oFEC	16QAM	OpenZR+ MSA	100G-400ZR-oFEC-16QAM-1-S	S
6	1 x 400GAUI-8	400G	OpenZR+	oFEC	16QAM	OpenZR+ MSA	400G-400ZR-oFEC-16QAM-1-E	E
7	2 x 200GAUI-4	400G	OpenZR+	oFEC	16QAM	OpenZR+ MSA	200G-400ZR-oFEC-16QAM-1-E	E
8	4 x 100GAUI-2	400G	OpenZR+	oFEC	16QAM	OpenZR+ MSA	400G-400ZR-oFEC-16QAM-1-E	E
9	3 x 100GAUI-2	300G	OpenZR+	oFEC	8QAM	OpenZR+ MSA	100G-300ZR-oFEC-8QAM-1-SE	S
10	1 x 200GAUI-2	200G	OpenZR+	oFEC	QPSK	OpenZR+ MSA	200G-200ZR-oFEC-QPSK-1-S	S
11	2 x 100GAUI-2	200G	OpenZR+	oFEC	QPSK	OpenZR+ MSA	100G-200ZR-oFEC-QPSK-1-S	S
12	1 x 100GAUI-2	100G	OpenZR+	oFEC	QPSK	OpenZR+ MSA	100G-100ZR-oFEC-QPSK-1-S	S

Absolute Maximum Ratings

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Power Supply Voltage	Vcc	3.135	3.3	3.465	V	1
Storage Temperature	Tstg	-40		85	°C	
Operating Case Temperature	Tc	15		75	°C	
Relative Humidity (Non-Condensing)	RH			85	%	
Optical Receiver Overload				1	dBm	2

Notes:

1. 3.3V ±5% measured at the electrical connector.
2. The optical input to the receiver should not exceed this value. Transmitters must never be directly connected to receivers before ensuring that proper optical attenuation is used.

Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Power Supply Voltage	V _{CC}	3.135	3.3	3.465	V	1
Power Supply Current	I _{CC}			8	A	2
Peak Sustained Current	I _{CC,sp}			8.7	A	3
Inrush Current	I _{CC,ip}			10.5	A	4
Power Dissipation	P _{DISS}			26.1	W	5
Power Consumption				2.75	W	6

Notes:

1. 3.3V ±5% measured at the electrical connector.
2. Steady state current.
3. Sustained peak current at high power enable.
4. Instantaneous peak current at high power enable.
5. At nominal power supply voltage.
6. Low-power mode.

Optical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Transmitter						
Average Output Power	P _o	-9		+1	dBm	1, 2, 3
Laser Linewidth				300	kHz	4
Output Power Stability		-0.5		+0.5	dB	5
Output Power Stability		-1		+1	dB	6
In-Band OSNR		38			dB/0.1nm	7
Out-of-Band OSNR – Narrowband		42			dB/0.1nm	8
Out-of-Band OSNR – Wideband		42			dB/0.1nm	9
Frequency Range		191.275		196.125	THz	10
Center Frequency		$\nu_T - 1.5$	ν_T	$\nu_T + 1.5$	GHz	11
Channel Spacing		6.25			GHz	12
Centre Wavelength Range	T λ	1528.58		1567.34	nm	
Centre Wavelength	T λ	$\lambda_T - 15$	λ_T	$\lambda_T + 15$	pm	
Receiver						
Maximum Rx Power				13	dBm	
Receiver Operating Wavelength	R λ	1528.58		1567.34	nm	
Receiver Sensitivity	S	-12		-21	dBm	13
	S	-15		-23	dBm	14
	S	-18		-29	dBm	15
	S	-20		-32	dBm	16
Receiver Overload	P _{OL}			1	dBm	17
Receiver Input Power Range		-12		1	dBm	18, 19
		-15		1	dBm	18, 20
		-18		1	dBm	18, 21
		-20		1	dBm	18, 22
Extended Receiver Input Power Range		-16		1	dBm	23
Acquisition Range		-3.6		3.6	GHz	24
Upstream Tx Linewidth		-300		300	kHz	
Transmitter VOA Dynamic Range		10			dB	25
OSNR Tolerance				22.5	dB	19
				19.5	dB	20
				14.8	dB	21
				11.5	dB	22
Crosstalk Tolerance				7	dB	26

Chromatic Dispersion Tolerance		-52,000	±13,000	+52,000	ps/nm	19, 27
		-100,000	±50,000	+100,000	ps/nm	20, 27
		-100,000	±50,000	+100,000	ps/nm	21, 27
		-160,000	±80,000	+160,000	ps/nm	22, 27

Notes:

1. Output power is coupled into a 9/125µm single-mode fibre.
2. The output power is settable in steps of 0.1dB within the specified wavelength range.
3. +1dBm tunable down to -9dBm.
4. Frequency stability relative to flex grid channel setting.
5. Provisioned power greater than the maximum available Tx power. Output power change over temperature and over time, measured over 10ms intervals.
6. Provisioned power less than the maximum available Tx power. Output power change over temperature and over time, measured over 10ms intervals.
7. The 0.1nm bandwidth for the IB OSNR refers to 12.5GHz optical bandwidth. Measured using the linear interpolation method with ±100GHz offset noise marker. For ZR application codes 0x01-0x03, IB OSNR is defined within the bandwidth of the Tx spectral excursion.
8. Measured in frequency range 191.275THz fs - 75GHz and fs + 75GHz ... 196.125THz. Noise power is measured in 12.5GHz RBW and referenced to 12.5GHz noise bandwidth.
9. Measured in frequency range 191.275THz fs - 150GHz and fs + 150GHz ... 196.125THz. Noise power is measured in 62.5GHz RBW and referenced to 12.5GHz noise bandwidth.
10. Per ITU-T G.694.1 DWDM grid definition.
11. Applies also to LO.
12. Supports 100, 75, 50, 12.5, and 6.25GHz frequency grids.
13. Minimum input power needed to achieve post-FEC BER≤10⁻¹⁵, ZR400-OFEC-16QAM, OSNR>36dB.
14. Minimum input power needed to achieve post-FEC BER≤10⁻¹⁵, ZR300-OFEC-8QAM, OSNR>36dB.
15. Minimum input power needed to achieve post-FEC BER≤10⁻¹⁵, ZR200-OFEC-QPSK, OSNR>36dB.
16. Minimum input power needed to achieve post-FEC BER≤10⁻¹⁵, ZR100-OFEC-QPSK, OSNR>36dB.
17. The optical input to the receiver should not exceed this value. Transmitters must never be directly connected to receivers before ensuring that proper optical attenuation is used. Aggregate power of all channels.
18. An input power in this range guarantees optimum OSNR performance.
19. ZR400-OFEC-16QAM.
20. ZR300-OFEC-8QAM.
21. ZR200-OFEC-QPSK.
22. ZR100-OFEC-QPSK.
23. With ≤1dB OSNR tolerance degradation.
24. Frequency offset between received carrier and LO.
25. With Tx VOA attenuation set to minimum.
26. Ratio of accumulated crosstalk channels to signal power.
27. Less than 0.5dB receiver sensitivity penalty compared to OSNR>36dB.

Pin Descriptions

Pin	Logic	Symbol	Name/Description	Notes
1		GND	Module Ground (Logic and Power Return Path).	1
2	CML-I	Tx2-	Transmit Differential Pairs from Host to Module.	
3	CML-I	Tx2+	Transmit Differential Pairs from Host to Module.	
4		GND	Module Ground (Logic and Power Return Path).	1
5	CML-I	Tx4-	Transmit Differential Pairs from Host to Module.	
6	CML-I	Tx4+	Transmit Differential Pairs from Host to Module.	
7		GND	Module Ground (Logic and Power Return Path).	1
8	LVTTL-I	ModSelL	Module Select.	
9	LVTTL-I	ResetL	Module Reset.	
10		VccRx	+3.3V Receiver Power Supply.	2
11	LVC MOS-I/O	SCL	2-Wire Serial Interface Clock.	3
12	LVC MOS-I/O	SDA	2-Wire Serial Interface Data.	3
13		GND	Module Ground (Logic and Power Return Path).	1
14	CML-O	Rx3+	Receive Differential Pairs from Module to Host.	
15	CML-O	Rx3-	Receive Differential Pairs from Module to Host.	
16		GND	Module Ground (Logic and Power Return Path).	1
17	CML-O	Rx1+	Receive Differential Pairs from Module to Host.	
18	CML-O	Rx1-	Receive Differential Pairs from Module to Host.	
19		GND	Module Ground (Logic and Power Return Path).	1
20		GND	Module Ground (Logic and Power Return Path).	1
21	CML-O	Rx2-	Receive Differential Pairs from Module to Host.	
22	CML-O	Rx2+	Receive Differential Pairs from Module to Host.	
23		GND	Module Ground (Logic and Power Return Path).	1
24	CML-O	Rx4-	Receive Differential Pairs from Module to Host.	
25	CML-O	Rx4+	Receive Differential Pairs from Module to Host.	
26		GND	Module Ground (Logic and Power Return Path).	1
27	LVTTL-O	ModPrsL	Module Present.	4
28		IntL	Interrupt.	5
29		VccTx	+3.3V Transmitter Power Supply.	2
30		Vcc1	+3.3V Power Supply.	2
31	LVTTL-I	LPMODE	Low-Power Mode.	
32		GND	Module Ground (Logic and Power Return Path).	1
33	CML-I	Tx3+	Transmit Differential Pairs from Host to Module.	
34	CML-I	Tx3-	Transmit Differential Pairs from Host to Module.	

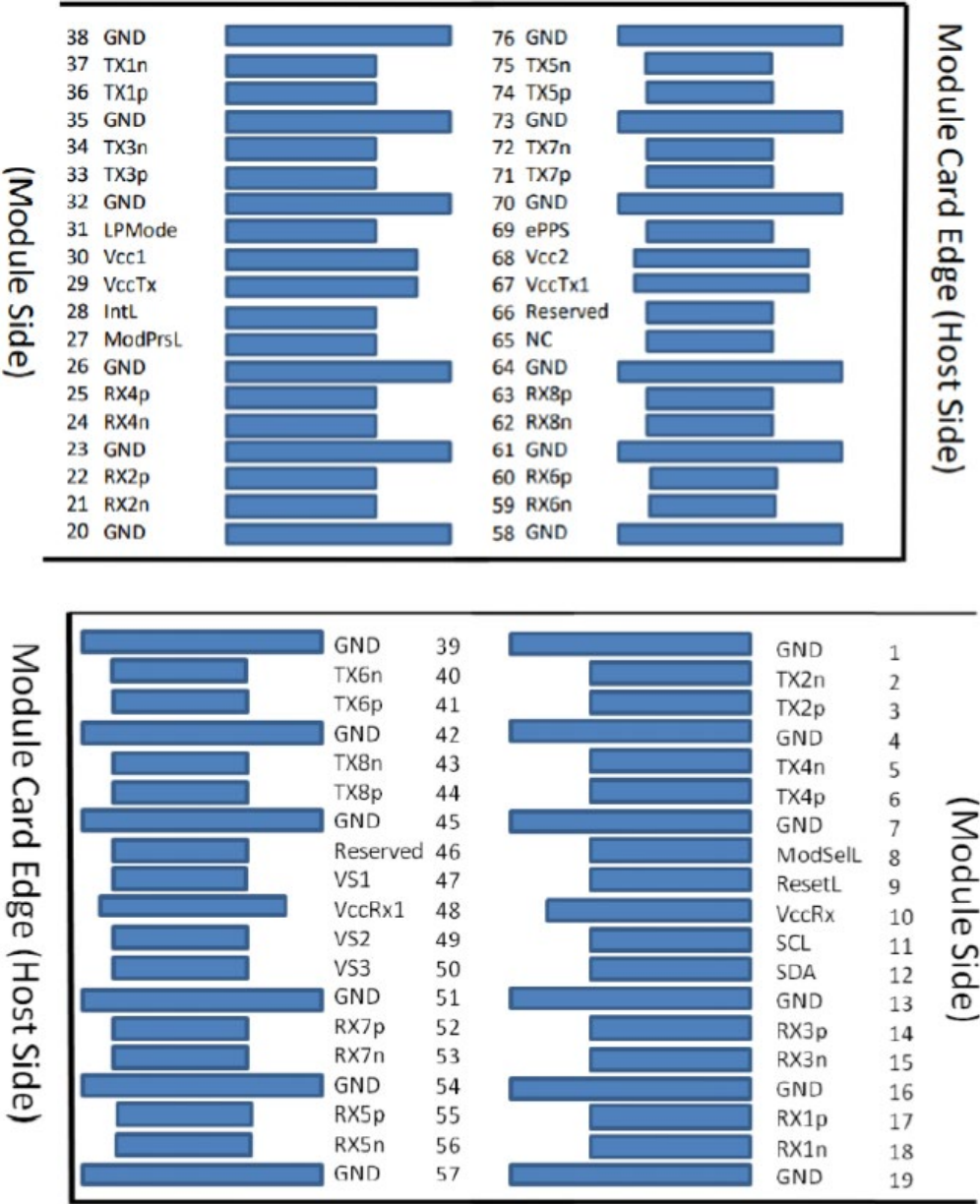
35		GND	Module Ground (Logic and Power Return Path).	1
36	CML-I	Tx1+	Transmit Differential Pairs from Host to Module.	
37	CML-I	Tx1-	Transmit Differential Pairs from Host to Module.	
38		GND	Module Ground (Logic and Power Return Path).	1
39		GND	Module Ground (Logic and Power Return Path).	1
40	CML-I	Tx6-	Transmit Differential Pairs from Host to Module.	
41	CML-I	Tx6+	Transmit Differential Pairs from Host to Module.	
42		GND	Module Ground (Logic and Power Return Path).	1
43	CML-I	Tx8-	Transmit Differential Pairs from Host to Module.	
44	CML-I	Tx8+	Transmit Differential Pairs from Host to Module.	
45		GND	Module Ground (Logic and Power Return Path).	1
46		Reserved	For Future Use. Not Connected.	6
47	LVC MOS-O	VS1	Module Vendor-Specific 1.	6
48		VccRx1	+3.3V Receiver Power Supply.	2
49	LVC MOS-I	VS2	Module Vendor-Specific 2.	6
50	LVC MOS-I/O	VS3	Module Vendor-Specific 3.	6
51		GND	Module Ground (Logic and Power Return Path).	1
52	CML-O	Rx7+	Receive Differential Pairs from Module to Host.	
53	CML-O	Rx7-	Receive Differential Pairs from Module to Host.	
54		GND	Module Ground (Logic and Power Return Path).	1
55	CML-O	Rx5+	Receive Differential Pairs from Module to Host.	
56	CML-O	Rx5-	Receive Differential Pairs from Module to Host.	
57		GND	Module Ground (Logic and Power Return Path).	1
58		GND	Module Ground (Logic and Power Return Path).	1
59	CML-O	Rx6-	Receive Differential Pairs from Module to Host.	
60	CML-O	Rx6+	Receive Differential Pairs from Module to Host.	
61		GND	Module Ground (Logic and Power Return Path).	1
62	CML-O	Rx8-	Receive Differential Pairs from Module to Host.	
63	CML-O	Rx8+	Receive Differential Pairs from Module to Host.	
64		GND	Module Ground (Logic and Power Return Path).	1
65		NC	Not Connected.	6
66		Reserved	For Future Use. Not Connected.	6
67		VccTx1	+3.3V Transmitter Power Supply.	2
68		Vcc2	+3.3V Power Supply.	2
69	LVTTL-I	ePPS	Precision Time Protocol (PTP) Reference Clock Input.	
70		GND	Module Ground (Logic and Power Return Path).	1

71	CML-I	Tx7+	Transmit Differential Pairs from Host to Module.	
72	CML-I	Tx7-	Transmit Differential Pairs from Host to Module.	
73		GND	Module Ground (Logic and Power Return Path).	1
74	CML-I	Tx5+	Transmit Differential Pairs from Host to Module.	
75	CML-I	Tx5-	Transmit Differential Pairs from Host to Module.	
76		GND	Module Ground (Logic and Power Return Path).	1

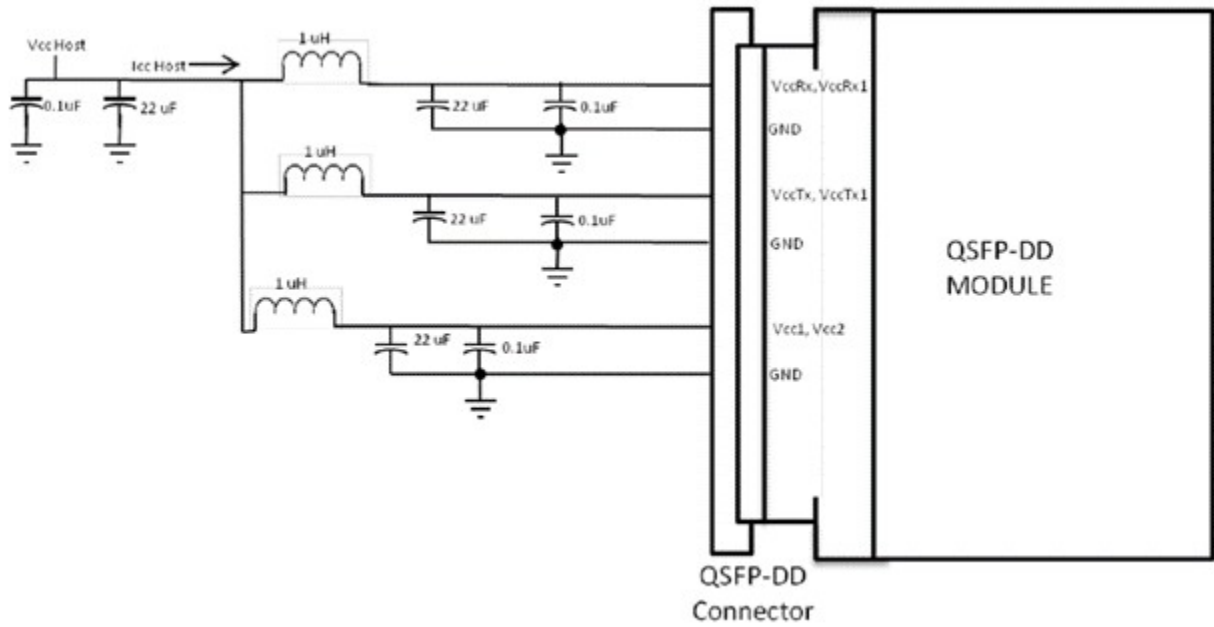
Notes:

1. QSFP-DD uses common ground (GND) for all signals and supply (power). All are common with the QSFP-DD module, and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal common ground plane.
2. VccRx, VccRx1, Vcc1, Vcc2, VccTx, and VccTx1 shall be applied concurrently. VccRx, VccRx1, Vcc1, Vcc2, VccTx, and VccTx1 are internally connected within the module. The connector Vcc pins are each rated for a maximum current of 1.0A.
3. Open drain. Requires 1.0k to 3.3k pull-up resistor to 3.3V on the host.
4. Indication from module to host. Requires 4.7k to 10k pull-up resistor to 3.3V on the host.
5. Open collector. Interrupt request from module to host. Requires 4.7k pull-up resistor to 3.3V on the host.
6. Reserved and NC pins may be terminated with 50Ω to ground on the host. Vendor-Specific and Reserved pads shall have an impedance to the GND that is greater than 10kΩ and is less than 100pF.

Electrical Pad Layout



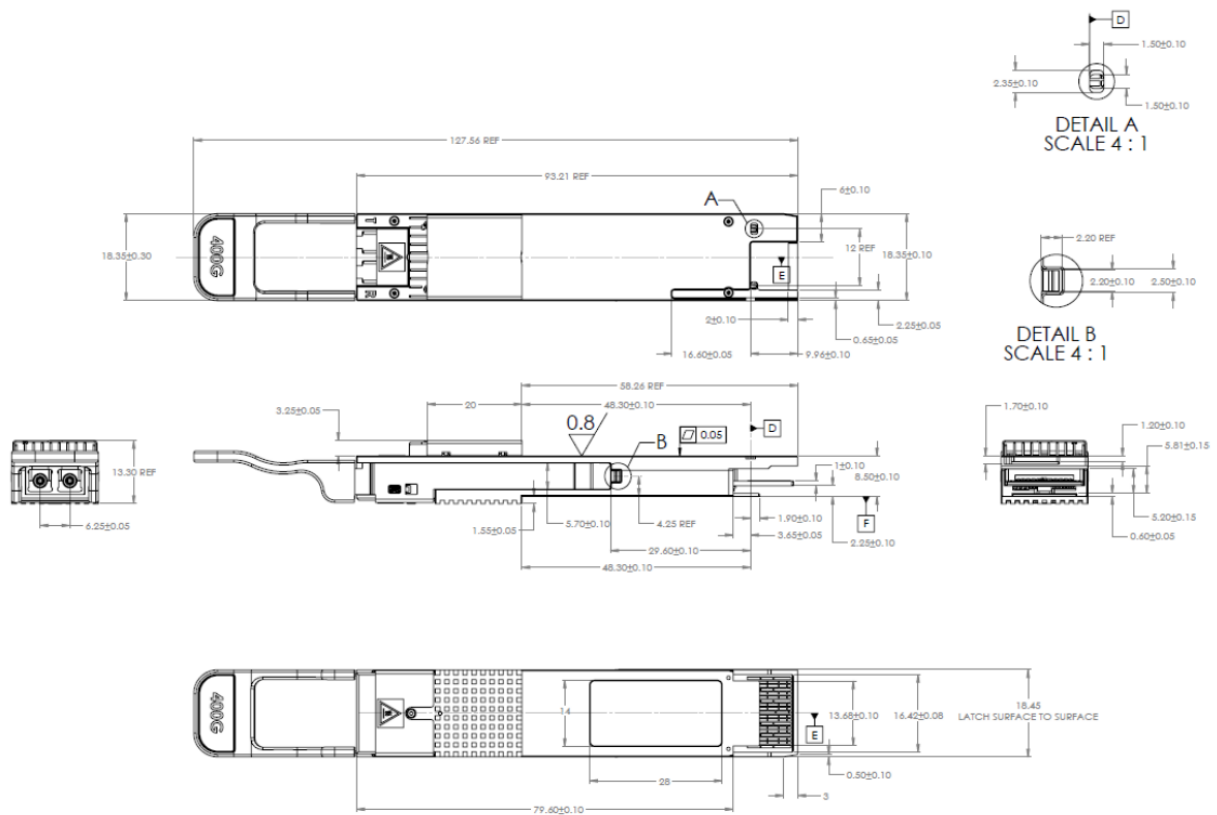
Recommended Power Supply Filter



Notes:

1. Filter capacitor values are informative vary depending on applications. Vcc1 and/or Vcc2 may be connected to the VccTx, VccTx1 or VccRx, VccRx1 provided the applicable derating of the maximum current limit is used.

Mechanical Specifications



About Skylane Optics

Skylane is a leading provider of transceivers for optical communication.

We offer an extensive portfolio for the enterprise, access, datacenter and metropolitan fiber optical market as well as for smart home applications and home networks.

We cover the European, South American and North American market with a strong partner network and have offices in Belgium, Brazil, Sweden and USA.

Our offerings are characterized by high quality and performance. In combination with our strong technical support, we enable our customers to build cost optimized network solutions.

We offer an extensive range of high-quality products including transceivers (Optical and copper), Active Optical Cable (AOC), Direct Attach Cable (DAC), Mux/Demux, Coding Box.

